

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
650V	720mΩ@10V	12A

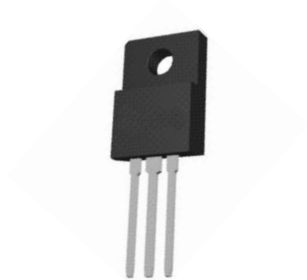
Feature

- Self-aligned planar Technology
- Low conduction loss

Application

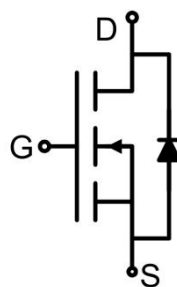
- Uninterruptible power supply (UPS)
- Power factor correction (PFC)

Package

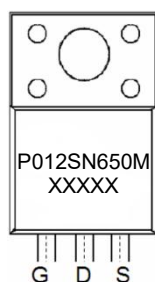


ITO-220AB

Circuit diagram



Marking



Absolute maximum ratings ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	650	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current	I_D	12	A
Pulsed Drain Current ¹⁾	I_{DM}	44	A
Single Pulse Avalanche Energy ²⁾	E_{AS}	304	mJ
Power Dissipation ³⁾	P_D	32.1	W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	3.9	$^{\circ}\text{C}/\text{W}$
Operating Junction Temperature	T_J	$-55 \sim +150$	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	$-55 \sim +150$	$^{\circ}\text{C}$

Electrical characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero gate voltage drain current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			1	μA
Gate-body leakage current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 30V$			± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3.5	4	V
Drain-source on-resistance ⁴⁾	$R_{DS(on)}$	$V_{GS}=10V, I_D=5.5A$		600	720	m Ω
Dynamic characteristics ⁵⁾						
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		1528		pF
Output Capacitance	C_{oss}			147		
Reverse Transfer Capacitance	C_{rss}			16		
Total Gate Charge	Q_g	$V_{DS}=520V, V_{GS}=10V, I_D=11A$		46		nC
Gate-Source Charge	Q_{gs}			7		
Gate-Drain Charge	Q_{gd}			23		
Turn-on delay time	$t_{d(on)}$	$V_{DS}=325V, I_D=11A, R_G=25\Omega$		43		nS
Turn-on rise time	t_r			29		
Turn-off delay time	$t_{d(off)}$			196		
Turn-off fall time	t_f			51		
Source-Drain Diode characteristics						
Diode Forward Current	I_S	$T_C=25^{\circ}C$			12	A
Diode Forward voltage	V_{SD}	$V_{GS}=0V, I_S=5.5A$			1.4	V
Reverse Recovery Time	T_{rr}	$V_{GS}=0V, I_S=11A$ $di/dt=100A/\mu s$		482		nS
Reverse Recovery Charge	Q_{rr}			2.85		μC

Notes:

- 1) The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2) The EAS data shows Max. rating $I_{AS}=11A, V_{DD}=50V, R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$.
- 3) The power dissipation is limited by 150°C junction temperature.
- 4) The test condition is Pulse Test: Pulse width $\leq 300\mu s$, Duty Cycle $\leq 1\%$.
- 5) Guaranteed by design, not subject to production testing.

Typical Characteristics

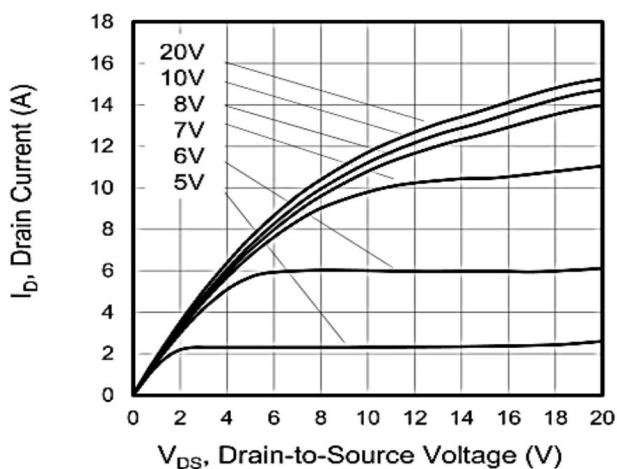


Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

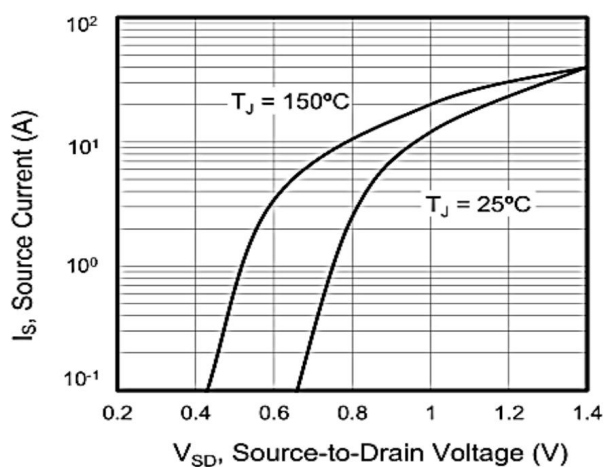


Figure 2. Body Diode Forward Voltage

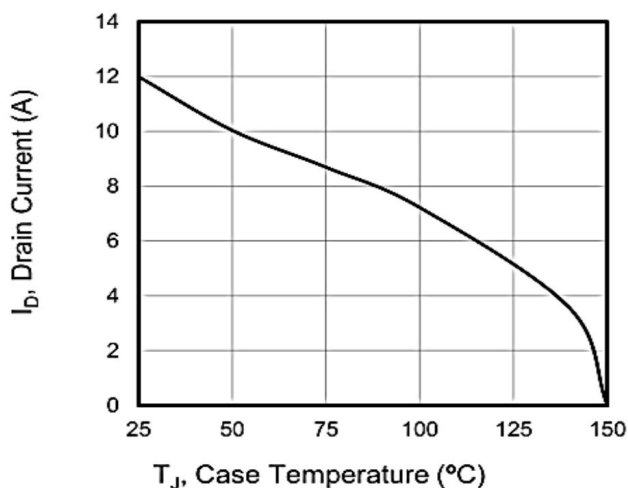


Figure 3. Drain Current vs. Temperature

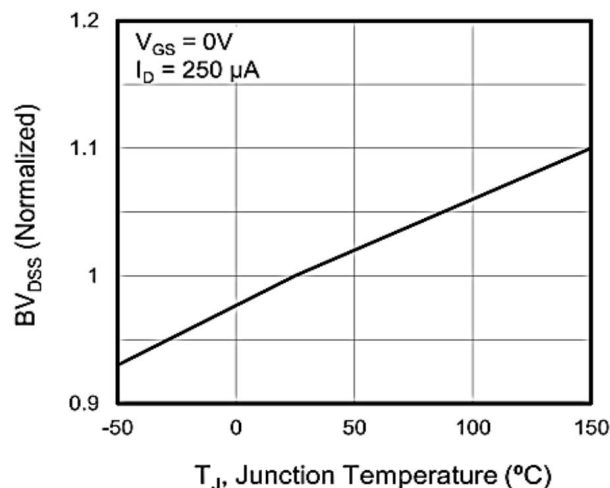


Figure 4. BV_{DSS} Variation vs. Temperature

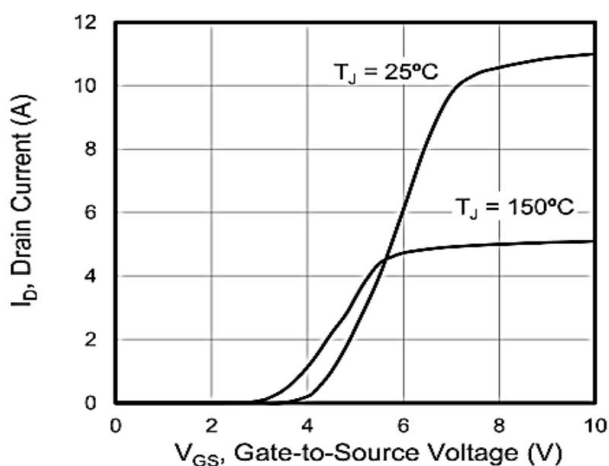


Figure 5. Transfer Characteristics

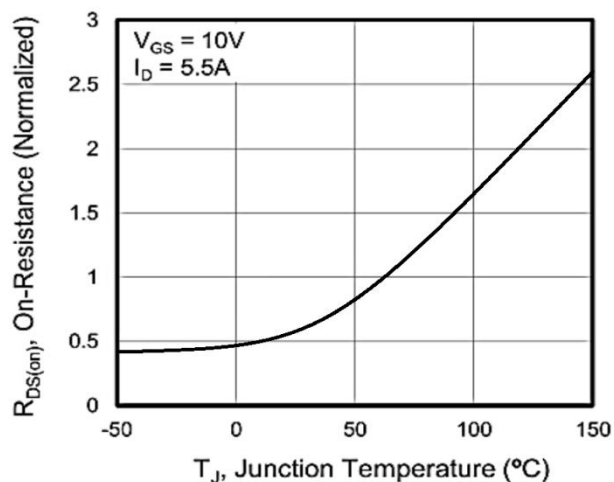


Figure 6. On-Resistance vs. Temperature

Typical Characteristics

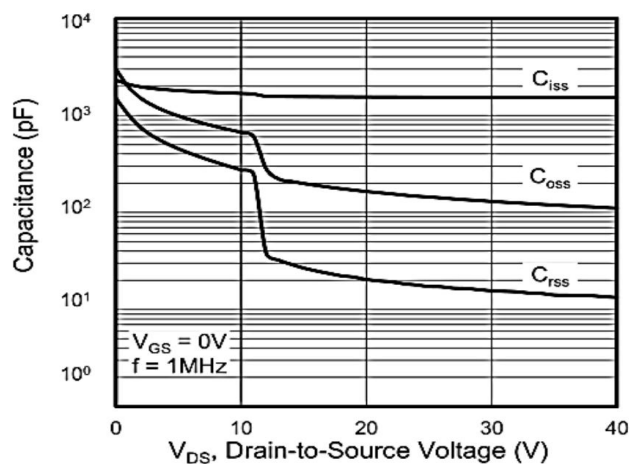
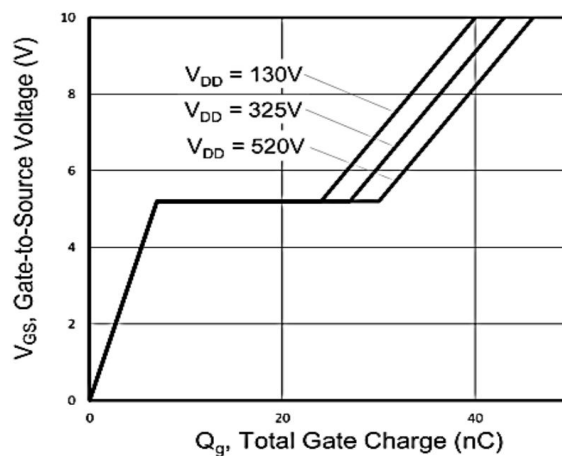


Figure 7. Capacitance Figure



8. Gate Charge

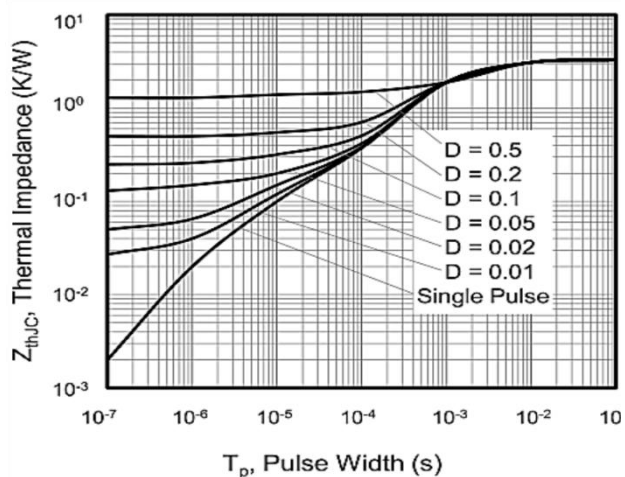
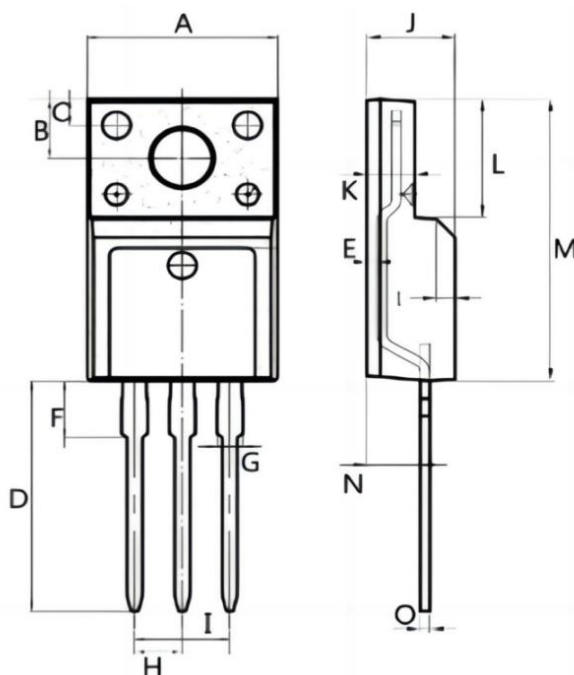


Figure 9. Transient Thermal Impedance

ITO-220AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.900	10.300	0.390	0.406
B	2.900	3.500	0.114	0.138
C	1.150	1.450	0.045	0.057
D	12.750	13.250	0.502	0.522
E	0.550	0.750	0.022	0.030
F	3.100	3.500	0.122	0.138
G	1.250	1.450	0.049	0.057
H	2.540 BSC.		0.100 BSC.	
I	5.080 BSC.		0.200 BSC.	
J	4.550	4.750	0.179	0.187
K	2.400	2.700	0.094	0.106
L	6.350	6.750	0.250	0.266
M	15.000	16.000	0.591	0.630
N	2.750	3.150	0.108	0.124
O	0.450	0.600	0.018	0.024